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REMTEC TO ATTEND IMS 2026
Company Will Demonstrate How It Advances RF, Microwave, and High-Power Electronics Through Advanced Ceramic Technology

Canton, MA -- **Remtec Incorporated**: When the RF and microwave industry's brightest minds gather in Boston this June for IMS 2026, one company will be showcasing technologies that are helping redefine what is possible in high-frequency, high-power, and mission-critical electronic applications. REMTEC will be exhibiting at Booth 22078 during IMS 2026, taking place June 7-12 at the Thomas M. Menino Convention & Exhibition Center in Boston, Massachusetts.

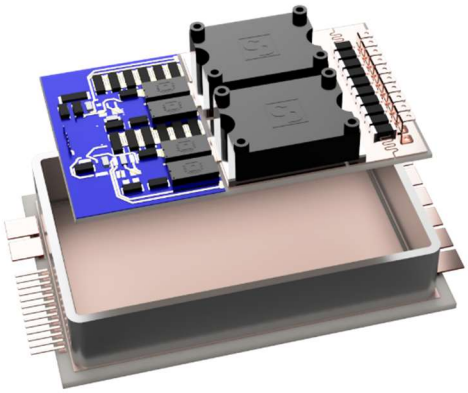

Figure 1: Hybrid Multilayer

For engineers designing next-generation RF systems, microwave devices, power electronics, aerospace systems, defense applications, medical equipment, and advanced communications infrastructure, REMTEC offers a unique combination of materials science expertise, advanced ceramic substrate technology, and decades of manufacturing experience.

IMS has long been recognized as the world's premier event for RF and microwave technology. The 2026 event is expected to attract more than 8,000 industry professionals and over 500 exhibitors from around the world, making it one of the most important gatherings for companies driving innovation in wireless communications, radar systems, satellite technology, aerospace electronics, and high-frequency applications.

For REMTEC, IMS provides an ideal venue to demonstrate how advanced ceramic circuit technologies are solving many of the challenges facing today's electronics designers.

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Why Ceramic Technology Matters More Than Ever

Electronic systems continue to become smaller, more powerful, and more demanding. Engineers are constantly being asked to deliver greater performance while simultaneously reducing size, weight, and power consumption.

Traditional circuit board technologies often struggle when confronted with extreme thermal requirements, high-frequency operation, or demanding environmental conditions. This is where advanced ceramic substrates provide a significant advantage.

REMTEC has spent more than three decades developing and manufacturing advanced ceramic circuits, substrates, packaging products, and interconnect technologies for some of the world's most demanding electronic applications. The company has established itself as a leader in thick film, thin film, direct bond copper, and proprietary Plated Copper Thick Film (PCTF®) technologies.

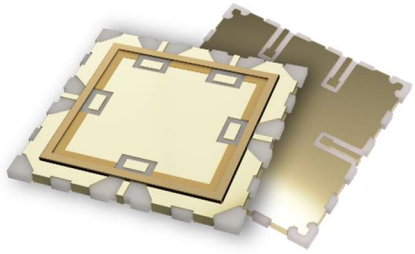

Figure 2: SMT Power

These technologies offer exceptional thermal performance, mechanical stability, electrical reliability, and high-frequency capabilities that make them especially valuable for RF and microwave applications.

Solutions Designed for High-Performance Applications

Visitors to the REMTEC booth will discover a broad portfolio of advanced ceramic solutions specifically engineered for challenging applications.

The company's thick film ceramic substrate technologies provide outstanding performance in high-density and high-power environments. These solutions support applications where thermal management, signal integrity, and reliability are critical design requirements.

REMTEC's direct bond copper substrates offer exceptional thermal conductivity and current-carrying capability, making them particularly attractive for power electronics, RF amplifiers, and demanding industrial applications.

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The company's proprietary PCTF® technology combines the advantages of thick film processing with plated copper conductors, delivering high-performance circuitry with enhanced electrical and thermal characteristics. This unique capability has helped position REMTEC as a leading supplier for advanced electronic packaging and substrate solutions.

Supporting the Evolution of RF and Microwave Design

As frequencies continue to increase and system requirements become more demanding, material selection has become a critical design consideration.

RF and microwave engineers are increasingly seeking substrate technologies that can maintain signal integrity while managing thermal loads and ensuring long-term reliability.

Ceramic substrates provide several advantages that make them particularly attractive for these applications:

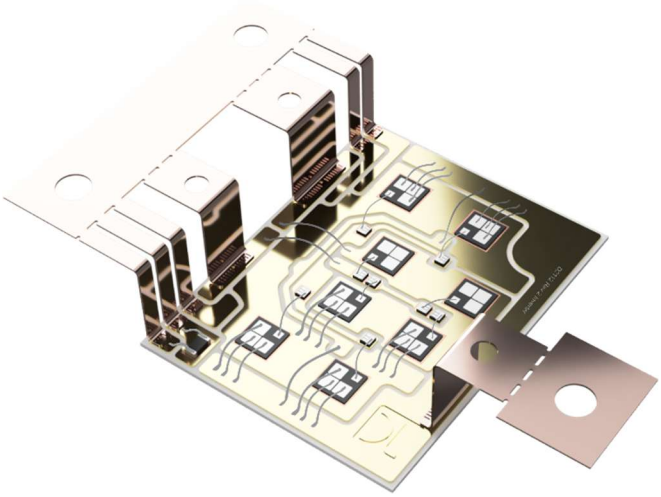

Figure 3: High Power

- Superior thermal conductivity enables efficient heat dissipation.
- Excellent dimensional stability supports precise circuit geometries.
- Outstanding environmental resistance ensures performance in harsh operating conditions.
- Low dielectric loss characteristics support high-frequency operation.
- Exceptional reliability contributes to longer product life cycles.

These advantages have made ceramic technologies an increasingly important component of modern RF and microwave system design.

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Applications Across Multiple Industries

One of the reasons REMTEC continues to gain attention throughout the electronics industry is the breadth of applications served by its technologies.

The company's advanced ceramic solutions are utilized in aerospace systems where reliability is non-negotiable:

- Defense applications benefit from the ability to operate in harsh environments while maintaining signal integrity and thermal performance.
- Medical electronics manufacturers rely on ceramic technologies for critical diagnostic and treatment systems that require long-term reliability and precision.
- Industrial power systems leverage ceramic substrates for thermal management and durability.
- Telecommunications and wireless infrastructure providers utilize ceramic technologies to support the performance requirements of increasingly sophisticated communications systems.

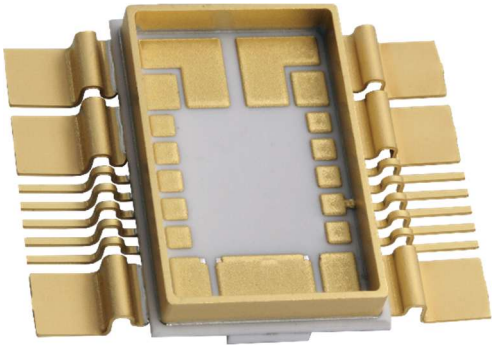

Figure 4: Leaded Power

This wide range of applications reflects the versatility and value of advanced ceramic packaging and substrate technologies.

Manufacturing Expertise That Makes the Difference

Technology alone is not enough.

Successful implementation requires manufacturing expertise, process control, and a deep understanding of application requirements.

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Since its founding in 1990, REMTEC has built a reputation for helping customers solve complex design and manufacturing challenges through collaborative engineering and advanced manufacturing capabilities. The company serves customers worldwide from its Massachusetts headquarters and has become a trusted partner for organizations requiring high-performance ceramic solutions.

Visitors to IMS will have the opportunity to discuss specific application requirements with REMTEC's technical experts and learn how ceramic technologies can improve performance, reliability, and manufacturability.

A Perfect Fit for IMS 2026

The theme of IMS has always been innovation, and REMTEC's technology portfolio aligns perfectly with the event's focus on advancing RF and microwave performance.

As wireless systems become more complex, as power densities continue to increase, and as engineers seek new ways to overcome traditional design limitations, advanced ceramic technologies are becoming increasingly important.

IMS attendees are searching for solutions that deliver measurable performance advantages. REMTEC delivers exactly that: Whether the challenge involves thermal management, high-frequency performance, power handling capability, environmental durability, or long-term reliability, the company's advanced ceramic technologies offer compelling solutions.

Visit REMTEC at Booth 22078

IMS 2026 represents an outstanding opportunity for engineers, designers, manufacturers, and industry leaders to explore the latest developments in RF and microwave technology.

Visitors to Booth 22078 will discover how REMTEC's advanced ceramic substrates, metallized ceramics, packaging solutions, and proprietary technologies are helping customers push the boundaries of electronic performance.

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As the RF and microwave industry continues to evolve, REMTEC remains committed to providing innovative solutions that help customers meet today's challenges while preparing for tomorrow's opportunities.

For companies seeking higher performance, greater reliability, and advanced thermal management capabilities, a visit to REMTEC's IMS 2026 exhibit should be high on the agenda.

The future of RF, microwave, and high-power electronics is being built on advanced materials and innovative engineering. REMTEC is proud to be helping lead the way.

For more information about REMTEC, visit REMTEC. For IMS 2026 event information, visit IMS 2026 Boston.

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About Remtec

Founded in 1990 and today operating out of a newly renovated, state-of-the-art facility in Canton, MA – Remtec Incorporated is an ISO 9001:2015 certified and RoHS and ITAR compliant U.S. company providing custom and semi-custom ceramics-based electronic packaging, assembly, substrate, and component solutions for a wide range electronics customers – and applied in challenging contexts within RF/microwave, power electronics, optoelectronics, defense, aerospace, and semiconductor manufacturing segments. Remtec is also a member of the Printed Circuit Board Association of America (PCBAA), a consortium of U.S.-based companies that support and advocates for U.S. domestic electronics production and related supply chains. The company is also a member of: PCEA, PMSA, iMaps, and the Global Electronics Organization (IPC). Learn more about Remtec at www.remtec.com.